

# On the way to Planar Optronic Systems

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SysInt 2014, Thursday July 3, 2014, in Bremen, Germany



## Acknowledgements

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Funded by **German Research Foundation** (Deutsche Forschungsgemeinschaft)

DFG



- Introduction
- Vision of sensor concepts
- > Materials
- Production methods
- > Characterization
- > Summary











- Light will be the main future media for signal transmission.
- Measured signals will be converted into light.
- Electrical signals will be exchanged for light signals.
- ➤ A fully optical world?
- > What do we need to get there?











#### Why optical technologies?





#### Why using photons?

- Variety of planar sensor concepts
- Low energy consumption
- High bandwidth
- Electro-magnetic compatibility
- Simple multiplexing
- High integration density on various scales











Planarity is the key to the integration and processability in parallel processes.



## Why using polymers?

- High functionality; versatile material class
- Modifiable to the application
- Efficient processability, even at high throughput, e.g. reel-to-reel process
- Simple build-up of large-scale systems
- Small layer thickness = high resource efficiency
- Hybrid-systems for trans-technology matrix structures possible









## Integration of electronics





## **Planar integration of optics**





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#### Possible and new sensor concepts

- Interferometric sensors
- Strain detection sensors
- Temperature detection sensors
- Whispering gallery mode sensors
- > Planar optical polymer foil spectrometer













#### **Mach-Zehnder interferometric sensor**



Fig. 15.1: S-bend funtions for Mach-Zehnder interferometer (Hofmann, 2014).

Fig. 15.2: Transmission within S-bends (Hofmann, 2014).

core layer

substrate

5000

6000



#### Planar integrated strain detection sensors





Kelb C, Reithmeier E, Roth B. Planar integrated polymer-based optical strain sensor. Proceedings of SPIE Photonics West 8977, 2014 MOEMS and Miniaturized Systems XIII, 89770Y (March 7, 2014)



#### Planar integrated temperature detection sensors



Suhir E., Lee Y. C., Wong C. P., Micro- and Opto-Electronic Materials and Structures: Physics, Mechanics, Design, Reliability, Packaging: Volume I, Springer, 2007. Weber M. J. Handbook of Optical Materials, CRC Press, 2003.



- Foil integrated Whispering-gallery mode sensors
- Resonant frequencies very sensitive to changes on surrounding refractive index
- Ultimate target sensitivity: single-molecule detection in liquid phase
- Simulation with RSoft



**Figure 20.1**: The microsphere is attached to one waveguide, another waveguide detects the transmitted signal.

- ✓ Ring-resonator: inner diameter 4.5  $\mu$ m, thickness 1  $\mu$ m, n=1.59
- $\checkmark$  The left waveguide is used as an excitation source: thickness 1 µm, n=1.46
- ✓ In case of resonance: light is coupled into the ring-resonator, dip in the transmission signal



Figure 20.2: Build-up of the electromagnetic field in the WGM of a 1  $\mu$ m thick ring resonator,  $\lambda$  = 1089 nm (Petermann, 2014).



## Planar optical polymer foil spectrometer - PolyAWG

- Simulations for singlemode waveguides
- Singlemode waveguide cores with either high aspect ratio or small dimensions (< 700 nm)</p>
- ZnO nanowires in substrate against mechanical strain



Fig. 21.1: Sketch of an AWG (TU Clausthal).



**Fig. 21.2:** Geometry (height x width) of the simulated waveguides (TU Clausthal).



**Fig. 21.3:** Simulations performed with PhotonDesing® FIMMWAVE, red bars represent the single-mode region (TU Clausthal).



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- > Target
  - Development of polymers with tailored optical & thermo-mechanical properties for polymer waveguides
- > Concept
  - ✓ Prepolymer synthesis with respect to
  - ✓ adjustable physical properties
  - ✓ use in a variety of shaping/molding techniques
- Prepolymer
  - ✓ adjustable viscosity  $(10^{-3} 10^2 \text{ Pa•s})$
  - ✓ UV/Vis curing favorable
- > Polymer
  - ✓ adjustable refractive index (1.39 < n < 1.65 @ 589 nm)
  - ✓ optical damping less than 1 dB/m
  - ✓ continuous operation temperature > 100°C







- > Prepolymer  $\rightarrow$  MMA/PMMA/1,3-Butandioldimethacrylate (BDMA)
- > Polymer  $\rightarrow$  Poly(methylmethacrylate-co-1,3-butandioldimethacrylate)
- ➢ Dopant → Phenanthrene





Fig. 25.1: Viscosity adjustment with prepolymer concentration, 5 Pa·s >  $\eta$  > 0.15 Pa·s, @100 1/s, 60°C (IMTEK, Freiburg).



**Fig. 25.2:** Refractive index change with dopant concentration, 1.49 < n < 1.55, @589 nm, 20 °C (IMTEK, Freiburg).



- Introduction
- Vision of sensor concepts
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- Production methods
- > Characterization
- > Summary













Fig. 29.1: Planar optronic sensor system; highlighted waveguide (Wang, 2014).

\* Wang, Y., L. Overmeyer, "Low temperature Optodic Bonding for Integration of Micro Optoelectronic Components in Polymer Optronic Systems", Procedia Technology, Elsevier, (accepted).



## Production concepts for integrated waveguides

- Laser processes
  - $\checkmark$  fs- laser processing
  - ✓ UV-photolithograghy
- Hot embossing and nano imprint
- > Printing
  - ✓ Offset
  - ✓ Flexographic
  - ✓ Inkjet
- Lamination and surface coating











#### Two-Photon-Polymerization (2PP)













**Fig. 33.1:** Polymer waveguides on a glass substrate (Zywietz, 2014).



Fig. 33.2: Single polymer waveguide fabricated by 2PP (Zywietz, 2014).



**Fig. 33.4:** Polymer waveguides on a highly flexible PMMA substrate (Zywietz, 2014).

\*Zywietz, U., C. Reinhardt, A.B. Evlyukhin, B.N. Chichkov, "Laser printing of silicon nanoparticles with resonant optical electric and magnetic responses", Nature Communications, 5, No. 3402, (2014).



#### Hot embossing of micro-optical components



Fig. 34.1: Fabricated optical waveguides through hot embossing (Rezem, 2014).



Fig. 34.2: Waveguide structures on a silicone embossing stamp (Rezem, Akin, 2014)



**Fig. 34.3:** Waveguide transmission losses as a function of the bend radius simulated in Zemax and RSoft (Rezem, 2014).

Fig. 34.4: Hot-embossing tool currently under development (Kelb, 2014).

- Manufacturing of coupling structures and waveguides in 350 µm-thin polymer foils
- Different coupling structures have been tested

Rezem, M., A. Günther, M. Rahlves, B. Roth, and E. Reithmeier, "Hot embossing of polymer optical waveguides for sensing applications", Procedia Technology, Elsevier, (accepted).

## High throughput production of optical waveguides

> Demand: Manufacture of planar waveguide network on polymer foil



Fig. 35.1: Flexographic printed waveguides; acrylate on PVC substrate (Wolfer, 2013).

> Approach:

Combination of two printing processes

- Flexographic printing for prestructuring of films with high throughput
- Inkjet printing for individual complement with high resolution

 Process requirements for large scale production:

 high throughput
 high resolution



Fig. 35.2: Process limits of printing methods (OE-A Roadmap).

Wolfer, Bollgruen, Mager, Overmeyer, Korvink (2014). Flexographic and inkjet printing of polymer optical waveguides for fully integrated sensor systems. Technology Procedia, Elsevier.



## High throughput production of optical waveguides

- Flexographic printing machines
  - ✓ Process development in laboratory scale
  - ✓ Verification on modified industrial scale printing machine



Fig. 36.1: Flexographic printing machine in laboratory scale, IGT F1 UV

## Inkjet printing machines



Fig. 36.3: Pixdro LP 50 (Source: Meyer Burger)



**Fig. 36.2:** Printing machine Speedmaster SM52 (Source: Heidelberger Druckmaschinen AG).



Fig. 36.4: Dimatix DMP 2831 (Source: Dimatix)

## High throughput production of optical waveguides

## Typical properties of printed multimode optical waveguides



**Table 2:** Typically achieved process properties (Wolfer, 2014).

| Property           | Value                 |  |  |  |
|--------------------|-----------------------|--|--|--|
| Width              | 20-1,000 µm           |  |  |  |
| Height             | <mark>4-110 µm</mark> |  |  |  |
| Max. aspect ratio  | 0.5                   |  |  |  |
| Speed of operation | 50-260 m²/h           |  |  |  |
| Surface roughness  | 12.5 nm               |  |  |  |

#### Waveguide setup in layers with parabolic shape



Fig. 38.2: Possible waveguide concepts by combining the core and cladding layers (Wolfer, 2014).

Wolfer, Bollgruen, Mager, Overmeyer, Korvink (2014). Flexographic and inkjet printing of polymer optical waveguides for fully integrated sensor systems. Technology Procedia, Elsevier.



#### What about active optical systems?



Fig. 43.1: Planar optronic sensor system; highlighted diodes (Wang, 2014).



## Optodic bonding as bridging technology

UV-curing

adhesive

- ≻ High success rate
   → 95 %
- Short process time
   → app. 10 s
- Mechanical strength
   → 23 N/mm<sup>2</sup>

Fig. 44.1 (right): Schematic illustration of optode for sideway irradiation (Wang, 2014)

0.112 Ω

0.286 Ω

- Electrical conductivity
  - ✓ panacol 4732: 0.292 Ω
  - ✓ Dymax OP-29: 0.169 Ω
  - ✓ Dymax OP-29-Gel:
  - ✓ Dymax OP-24-Rev-B: 0.110 Ω
  - ✓ Delo GB368:



Bonding
head

Chip

UV-radiation

Transparent

polymer substrate

**Fig. 44.2:** Photo of realized optode, (Low Temperature Optodic Bonding for Integration of Micro Optoelectronic Components in Polymer Optronic Systems, Wang et al., SysInt 2014, accepted).



## Integration of OLEDs and OPDs into waveguide systems

- Waveguide integrated device for detection at 634 nm
  - ✓ ITO on polymer waveguide
  - $\checkmark$  Structure optimization for high responsivity
- Optical simulations of OPD/waveguide structures
  - ✓ Mode distribution
  - ✓ Waveguide losses (loss channels)









#### **Photodetector operation parameters**





#### Laser-active waveguides



Kwon, Y.K., J.K. Han, J.M. Lee, Y.S. Koo, J.H. Oh, H.-S. Lee, E.-H. Lee, "Organic-inorganic hybrid materials for flexible optical waveguide applications", J. Mater. Chem., 18, 579-585, DOI: 10.1039/B715111J, (2008).



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#### **Measurement of optical transmission properties**

- Attenuation of waveguides
- Refraction index distribution
- Light dispersion in waveguides
- Coupling efficiency between interfaces
- ⇒ Some examples of spectral measurement equipment











- Light sources
  - ✓ LED, including confocal pattern for end face characterization
  - ✓ Diode laser (638 nm, 140 mW)
- Numerical aperture stapless variable within 0.1-0.5
- Aperture sizes: 1-1,000 μm



Fig. 51.1: End face of printed waveguide in optical measurement setup with focused LED spot (Wolfer, 2014).



Fig. 51.2: Optical measurement setup (Dumke, ITA, 2014).



#### **Refractive index measurements**

#### Hot embossing



**Fig. 53.1:** Epocore waveguides structured on a silicon wafer (Günther, 2014).

- Epocore waveguides structured on a silicon wafer
  - ✓ Substrate: silicon
  - ✓ Core material: epocore
  - ✓ Resolution 1.25 µm/pixel

#### fs-laser direct writing



**Fig. 53.2:** Waveguide written by laser direct writing into the substrate (Günther, 2014).

- Profilometer specifications
  - ✓ Refractive index resolution up to 10<sup>-4</sup>
  - ✓ Spatial resolution: 0.5 µm
  - Wavelength: 405 nm, 635 nm, 845 nm, 1320 nm



- Introduction
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- > Materials
- Production methods
- > Characterization
- > Summary











## Sensors for excellent flight performances ...





## ... and for stress and temperature surveillance





- Planar sensors concepts for measurement of
  - ✓ Temperature
  - ✓ Strain
  - $\checkmark$  Liquid and gaseous analytes
- Development of thermo-mechanical and chemical stable as well as refractive index tailored polymers
- High throughput production of waveguides in reelto-reel process - a combination of
  - ✓ Printing
  - ✓ Hot embossing
  - ✓ Laser processing
  - ✓ Lithography
- Optodical bonding as bridging technology
- Equipment available for characterization of
  - ✓ Refractive index
  - ✓ Thickness
  - ✓ Attenuation
  - ✓ Form stability
  - ✓ Glass transition temperature







